AN99 • AN115 • AN124 • AN133 • AN134 • AN135

Single Supply / Low Power / 256-tap / SPI bus



X9271

Single Digitally-Controlled (XDCP™) Potentiometer

FEATURES

- 256 Resistor Taps
- SPI Serial Interface for write, read, and transfer operations of the potentiometer
- Wiper Resistance, 100Ω typical @ V_{CC} = 5V
- 16 Nonvolatile Data Registers
- Nonvolatile Storage of Multiple Wiper Positions
- Power On Recall. Loads Saved Wiper Position on Power Up.
- Standby Current < 3µA Max
- V_{CC}: 2.7V to 5.5V Operation
- 50K Ω , 100K Ω versions of End to End Resistance
- 100 yr. Data Retention
- Endurance: 100,000 Data Changes per Bit per Register
- 14-Lead TSSOP, 16-Lead CSP (Chip Scale Package)
- Low Power CMOS

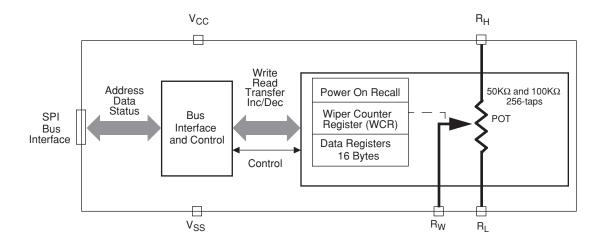
DESCRIPTION

The X9271 integrates a single digitally controlled potentiometer (XDCP) on a monolithic CMOS integrated circuit.

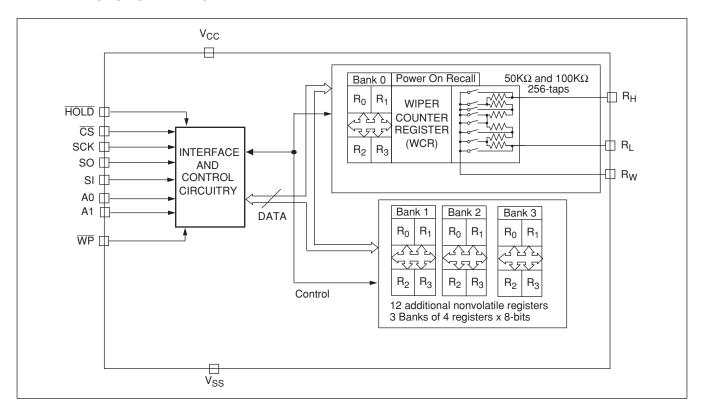
The digital controlled potentiometer is implemented using 255 resistive elements in a series array. Between each element are tap points connected to the wiper terminal through switches. The position of the wiper on the array is controlled by the user through the SPI bus interface. The potentiometer has associated with it a volatile Wiper Counter Register (WCR) and a four nonvolatile Data Registers that can be directly written to and read by the user. The contents of the WCR controls the position of the wiper on the resistor array though the switches. Powerup recalls the contents of the default data register (DR0) to the WCR.

The XDCP can be used as a three-terminal potentiometer or as a two terminal variable resistor in a wide variety of applications including control, parameter adjustments, and signal processing.

FUNCTIONAL DIAGRAM



DETAILED FUNCTIONAL DIAGRAM



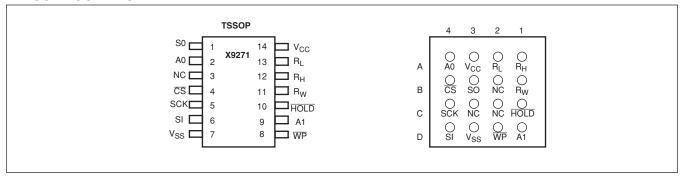
CIRCUIT LEVEL APPLICATIONS

- · Vary the gain of a voltage amplifier
- Provide programmable dc reference voltages for comparators and detectors
- · Control the volume in audio circuits
- Trim out the offset voltage error in a voltage amplifier circuit
- Set the output voltage of a voltage regulator
- Trim the resistance in Wheatstone bridge circuits
- Control the gain, characteristic frequency and Q-factor in filter circuits
- Set the scale factor and zero point in sensor signal conditioning circuits
- Vary the frequency and duty cycle of timer ICs
- Vary the dc biasing of a pin diode attenuator in RF circuits
- Provide a control variable (I, V, or R) in feedback circuits

SYSTEM LEVEL APPLICATIONS

- · Adjust the contrast in LCD displays
- Control the power level of LED transmitters in communication systems
- Set and regulate the DC biasing point in an RF power amplifier in wireless systems
- Control the gain in audio and home entertainment systems
- Provide the variable DC bias for tuners in RF wireless systems
- Set the operating points in temperature control systems
- Control the operating point for sensors in industrial systems
- Trim offset and gain errors in artificial intelligent systems

PIN CONFIGURATION



PIN ASSIGNMENTS

TSSOP	CSP	Symbol	Function
1	В3	SO	Serial Data Output.
2	A4	A0	Device Address.
3	B2, C2, C3	NC	No Connect.
4	B4	CS	Chip Select.
5	C4	SCK	Serial Clock.
6	D4	SI	Serial Data Input.
7	D3	V _{SS}	System Ground.
8	D2	WP	Hardware Write Protect.
9	D1	A1	Device Address.
10	C1	HOLD	Device select. Pause the serial bus.
11	B1	R _W	Wiper Terminal of the Potentiometer.
12	A1	R _H	High Terminal of the Potentiometer.
13	A2	R_{L}	Low Terminal of the Potentiometer.
14	A3	V _{CC}	System Supply Voltage.

PIN DESCRIPTIONS

Bus Interface Pins

SERIAL OUTPUT (SO)

SO is a serial data output pin. During a read cycle, data is shifted out on this pin. Data is clocked out by the falling edge of the serial clock.

SERIAL INPUT

SI is the serial data input pin. All opcodes, byte addresses and data to be written to the pots and pot registers are input on this pin. Data is latched by the rising edge of the serial clock.

SERIAL CLOCK (SCK)

The SCK input is used to clock data into and out of the X9271.

HOLD (HOLD)

HOLD is used in conjunction with the $\overline{\text{CS}}$ pin to select the device. Once the part is selected and a serial sequence is underway, $\overline{\text{HOLD}}$ may be used to pause the serial communication with the controller without resetting the serial sequence. To pause, $\overline{\text{HOLD}}$ must be brought LOW while SCK is LOW. To resume communication, $\overline{\text{HOLD}}$ is brought HIGH, again while SCK is LOW. If the pause feature is not used, $\overline{\text{HOLD}}$ should be held HIGH at all times. CMOS level input.

Device Address (A1 - A0)

The address inputs are used to set the the 8-bit slave address. A match in the slave address serial data stream must be made with the address input in order to initiate communication with the X9271.

CHIP SELECT (CS)

When \overline{CS} is HIGH, the X9271 is deselected and the SO pin is at high impedance, and (unless an internal write cycle is underway) the device will be in the standby state. \overline{CS} LOW enables the X9271, placing it in the active power mode. It should be noted that after a power-up, a HIGH to LOW transition on \overline{CS} is required prior to the start of any operation.

Potentiometer Pins

R_H, R_L

The R_H and R_L pins are equivalent to the terminal connections on a mechanical potentiometer.

Rw

The wiper pin are equivalent to the wiper terminal of a mechanical potentiometer.

Supply Pins

System Supply Voltage (VCC) and Supply Ground (VSS)

The V_{CC} pin is the system supply voltage. The V_{SS} pin is the system ground.

Other Pins

HARDWARE WRITE PROTECT INPUT (WP)

The WP pin when LOW prevents nonvolatile writes to the Data Registers.

No CONNECT.

No connect pins should be left floating. This pins are used for Xicor manufacturing and testing purposes.

PRINCIPLES OF OPERATION

Device Description

SERIAL INTERFACE

The X9271 supports the SPI interface hardware conventions. The device is accessed via the SI input with data clocked in on the rising SCK. $\overline{\text{CS}}$ must be LOW and the $\overline{\text{HOLD}}$ and $\overline{\text{WP}}$ pins must be HIGH during the entire operation.

The SO and SI pins can be connected together, since they have three state outputs. This can help to reduce system pin count.

ARRAY DESCRIPTION

The X9271 is comprised of a resistor array (see Figure 1). The array contains the equivalent of 255 discrete resistive segments that are connected in series. The

physical ends of each array are equivalent to the fixed terminals of a mechanical potentiometer (R_H and R_L inputs).

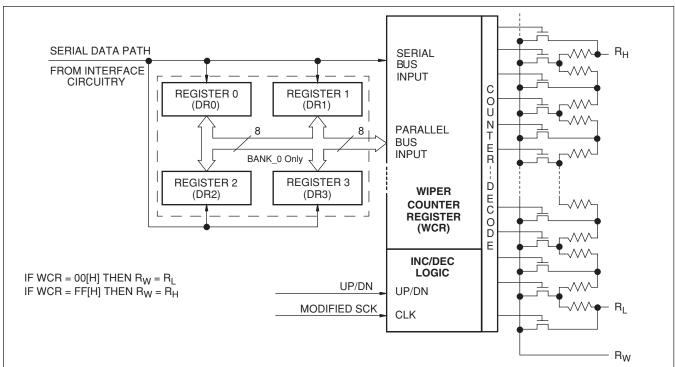
At both ends of each array and between each resistor segment is a CMOS switch connected to the wiper (R_W) output. Within each individual array only one switch may be turned on at a time.

These switches are controlled by a Wiper Counter Register (WCR). The 8-bits of the WCR (WCR[7:0]) are decoded to select, and enable, one of 256 switches (see Table 1).

POWER UP AND DOWN RECOMMENDATIONS.

There are no restrictions on the power-up or power-down conditions of V_{CC} and the voltages applied to the potentiometer pins provided that V_{CC} is always more positive than or equal to V_H , V_L , and V_W , i.e., $V_{CC} \ge V_H$, V_L , V_W . The V_{CC} ramp rate specification is always in effect.

Figure 1. Detailed Potentiometer Block Diagram



DEVICE DESCRIPTION

Wiper Counter Register (WCR)

The X9271 contains a Wiper Counter Register for the DCP potentiometer. The Wiper Counter Register can be envisioned as a 8-bit parallel and serial load counter with its outputs decoded to select one of 256 switches along its resistor array. The contents of the WCR can be altered in four ways: it may be written directly by the host via the Write Wiper Counter Register instruction (serial load); it may be written indirectly by transferring the contents of one of four associated data registers via the XFR Data Register instruction (parallel load); it can be modified one step at a time by the Increment/ Decrement instruction. Finally, it is loaded with the contents of its Data Register zero (DR0) upon power-up.

The Wiper Counter Register is a volatile register; that is, its contents are lost when the X9271 is powered-down. Although the register is automatically loaded with the value in DR0 upon power-up, this may be different from the value present at power-down. Power-up guidelines are recommended to ensure proper loadings of the R0 value into the WCR. The DR0 value of Bank 0 is the default value.

Data Registers (DR3-DR0)

The potentiometer has four 8-bit nonvolatile Data Registers. These can be read or written directly by the host. Data can also be transferred between any of the four Data Registers and the associated Wiper Counter Register. All operations changing data in one of the Data Registers is a nonvolatile operation and will take a maximum of 10ms.

If the application does not require storage of multiple settings for the potentiometer, the Data Registers can be used as regular memory locations for system parameters or user preference data.

Bits [7:0] are used to store one of the 256 wiper positions or data (0 \sim 255).

Status Register (SR)

This 1-bit Status Register is used to store the system status.

WIP: Write In Progress status bit, read only.

- When WIP=1, indicates that high-voltage write cycle is in progress.
- When WIP=0, indicates that no high-voltage write cycle is in progress

Table 1. Wiper counter Register, WCR (8-bit), WCR[7:0]: Used to store the current wiper position (Volatile, V).

WCR7	WCR6	WCR5	WCR4	WCR3	WCR2	WCR1	WCR0
V	V	V	V	V	V	V	V
(MSB)							(LSB)

Table 2. Data Register, DR (8-bit), DR[7:0]: Used to store wiper positions or data (Nonvolatile, NV).

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
NV							
MSB							LSB

Table 3. Status Register, SR (WIP is 1-bit)

WIP (LSB)

DEVICE DESCRIPTION

Instructions

IDENTIFICATION BYTE (ID AND A)

The first byte sent to the X9271 from the host, following a CS going HIGH to LOW, is called the Identification byte. The most significant four bits of the slave address are a device type identifier. The ID[3:0] bits is the device id for the X9271; this is fixed as 0101[B] (refer to Table 4).

The A1-A0 bits in the ID byte is the internal slave address. The physical device address is defined by the state of the A1-A0 input pins. The slave address is externally specified by the user. The X9271 compares the serial data stream with the address input state; a successful compare of both address bits is required for the X9271 to successfully continue the command sequence. Only the device which slave address matches the incoming device address sent by the master executes the instruction. The A1-A0 inputs can be actively driven by CMOS input signals or tied to $V_{\rm CC}$ or $V_{\rm SS}$.

INSTRUCTION BYTE (I[3:0])

The next byte sent to the X9271 contains the instruction and register pointer information. The three most significant bits are used provide the instruction opcode (I[3:0]). The RB and RA bits point to one of the four Data Registers. P0 is the POT selection; since the X9271 is single POT, the P0=0. The format is shown in Table 5.

REGISTER BANK SELECTION (R1, R0, P1, P0)

There are 16 registers organized into four banks. Bank 0 is the default bank of registers. Only Bank 0 registers can be used for data register to Wiper Counter Register operations.

Banks 1, 2, and 3 are additional banks of registers (12 total) that can be used for SPI write and read operations. The data registers in Banks 1, 2, and 3 cannot be used for direct read/write operations between the Wiper Counter Register.

Register Selection (DR0 to DR3) Table

		Register	
RB	RA	Selection	Operations
0	0	0	Data Register Read and Write; Wiper Counter Register Operations
0	1	1	Data Register Read and Write; Wiper Counter Register Operations
1	0	2	Data Register Read and Write; Wiper Counter Register Operations
1	1	3	Data Register Read and Write; Wiper Counter Register Operations

Register Bank Selection (Bank 0 to Bank 3) Table

		Bank	
P1	P0	Selection	Operations
0	0	0	Data Register Read and Write; Wiper Counter Register Operations
0	1	1	Data Register Read and Write Only
1	0	2	Data Register Read and Write Only
1	1	3	Data Register Read and Write Only

Table 4. Identification Byte Format

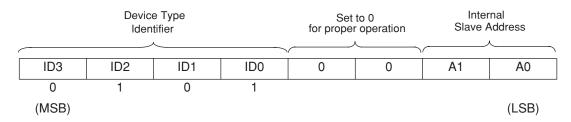
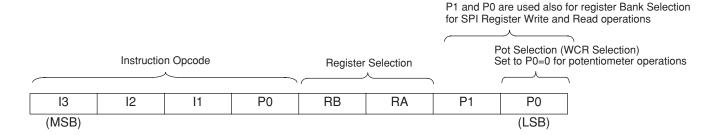


Table 5. Instruction Byte Format



DEVICE DESCRIPTION

Instructions

Five of the eight instructions are three bytes in length. These instructions are:

- Read Wiper Counter Register read the current wiper position of the potentiometer;
- Write Wiper Counter Register change current wiper position of the potentiometer;
- Read Data Register read the contents of the selected Data Register;
- Write Data Register write a new value to the selected Data Register.
- Read Status This command returns the contents of the WIP bit which indicates if the internal write cycle is in progress.

The basic sequence of the three byte instructions is illustrated in Figure 3. These three-byte instructions exchange data between the WCR and one of the Data Registers. A transfer from a Data Register to a WCR is essentially a write to a static RAM, with the static RAM controlling the wiper position. The response of the wiper to this action will be delayed by t_{WRL} . A transfer from the WCR (current wiper position), to a Data Register is a write to nonvolatile memory and takes a minimum of t_{WR} to complete. The transfer can occur between one of the four potentiometers and one of its associated registers; or it may occur globally, where the transfer occurs between all potentiometers and one associated register. The Read Status Register instruction is the only unique format (see Figure 4).

Two instructions require a two-byte sequence to complete (Figure 2). These instructions transfer data between the host and the X9271; either between the host and one of the data registers or directly between the host and the Wiper Counter Register. These instructions are:

- XFR Data Register to Wiper Counter Register –
 This transfers the contents of one specified Data
 Register to the associated Wiper Counter Register.
- XFR Wiper Counter Register to Data Register –
 This transfers the contents of the specified Wiper
 Counter Register to the specified associated Data
 Register.

The final command is Increment/Decrement (Figure 5 and 6). It is different from the other commands, because it's length is indeterminate. Once the command is issued, the master can clock the selected wiper up and/or down in one resistor segment steps; thereby, providing a fine tuning capability to the host. For each SCK clock pulse (t_{HIGH}) while SI is HIGH, the selected wiper will move one resistor segment towards the R_{H} terminal. Similarly, for each SCK clock pulse while SI is LOW, the selected wiper will move one resistor segment towards the R_{H} terminal.

See Instruction format for more details.

Write in Process (WIP bit)

The contents of the Data Registers are saved to nonvolatile memory when the \overline{CS} pin goes from LOW to HIGH after a complete write sequence is received by the device. The progress of this internal write operation can be monitored by a Write In Process bit (WIP). The WIP bit is read with a Read Status command.

Figure 2. Two-Byte Instruction Sequence

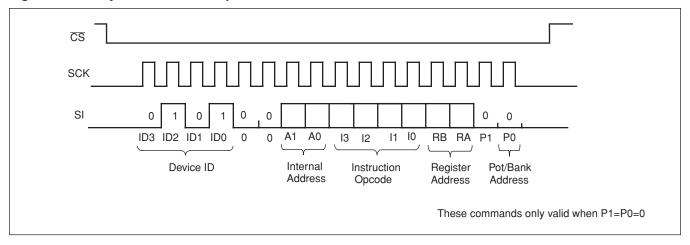


Figure 3. Three-Byte Instruction Sequence (Write)

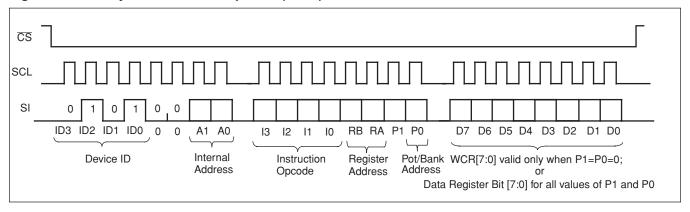


Figure 4. Three-Byte Instruction Sequence (Read)

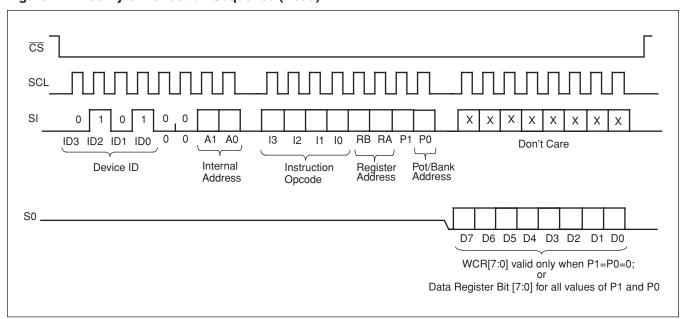


Figure 5. Increment/Decrement Instruction Sequence

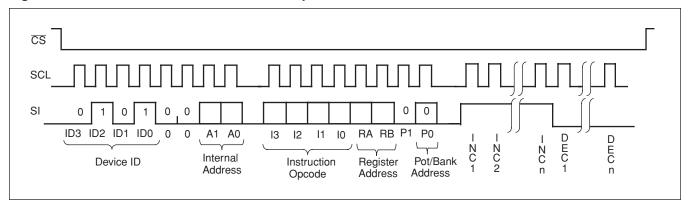


Figure 6. Increment/Decrement Timing Limits

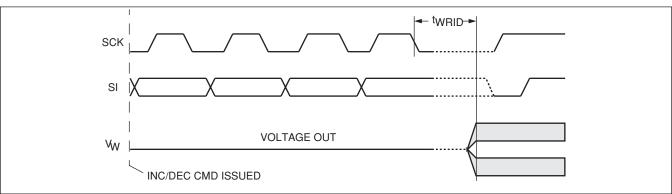


Table 6. Instruction Set

			In	stru	ction	Set			
Instruction	13	12	11	10	RB	RA	P ₁	P ₀	Operation
Read Wiper Counter Register	1	0	0	1	0	0	0	1/0	Read the contents of the Wiper Counter Register
Write Wiper Counter Register	1	0	1	0	0	0	0	1/0	Write new value to the Wiper Counter Register
Read Data Register	1	0	1	1	1/0	1/0	1/0	1/0	Read the contents of the Data Register pointed to by P1-P0 and RB-RA
Write Data Register	1	1	0	0	1/0	1/0	1/0	1/0	Write new value to the Data Register pointed to by P1-P0 and RB-RA
XFR Data Register to Wiper Counter Register	1	1	0	1	1/0	1/0	0	0	Transfer the contents of the Data Register pointed to by RB-RA (Bank 0 only) to the Wiper Counter Register
XFR Wiper Counter Register to Data Register	1	1	1	0	1/0	1/0	0	0	Transfer the contents of the Wiper Counter Register to the Register pointed to by RB-RA (Bank 0 only)
Increment/Decrement Wiper Counter Register	0	0	1	0	0	0	0	0	Enable Increment/decrement of the Wiper Counter Register
Read Status (WIP bit)	0	1	0	1	0	0	0	1	Read the status of the internal write cycle, by checking the WIP bit.

Note: 1/0 = data is one or zero

INSTRUCTION FORMAT

Read Wiper Counter Register (WCR)

<u>cs</u>		evice den	-	•	A		evice ress			stru Opc					Ban esse		(5	ا Sen	Nip t by					D)	CS
Falling Edge	0	1	0	1	0	0	A1	A0	1	0	0	1	0	0	0	0	W C R 7	WCR 6	WCR5	WCR4	W C R 3	W C R 2	W C R 1	W C R o	Rising Edge

Write Wiper Counter Register (WCR)

<u>cs</u>		evice Iden	-	•	A		evice ress			stru Opc					Banl esse			(Se	D nt b		Byt lost		SI)		CS
Falling Edge	0	1	0	1	0	0	A1	A0	1	0	1	0	0	0	0	0	W C R 7	W C R 6	W C R 5	W C R 4	W C R 3	W C R 2	W C R 1	W C R o	Rising Edge

Read Data Register (DR)

	CS Falling		evice Iden	,	•	Δ		vice esse		Ι.	_	ctic ode		A		Bank esse:			(Se			Byte 271		SO)		CS Rising
ı	Edge	0	1	0	1	0	0	A1	A0	1	0	1	1	RB	RA	P1	P0	D7	D 6	D5	D4	D3	D2	D1	D0	Edge

Write Data Register (DR)

CS			e Ty	•			evice ress			stru Opc				DR/I				(8		Data by F	•		il)		cs	TAGE
Falling Edge	0	1	0	1	0	0	A1	A0	1	1	0	0	RB	RA	P1	P0	D7	D 6	D5	D4	D3	D2	D1	D0	Rising Edge	HIGH-VOL WRITE C

Transfer Wiper Counter Register (WCR) to Data Register (DR)

CS		Эe	vice	э Ту	ре		De	evice)	In	stru	ıctio	on	[DR/Ba	ınk		CS	LUCLLVOLTAGE
Falling		lo	den	tifie	r	/	4dd	ress	es	(Эрс	ode	9	Α	ddres	ses		Rising	HIGH-VOLTAGE WRITE CYCLE
Edge	C)	1	0	1	0	0	A1	A0	1	1	1	0	RB	RA	0	0	Edge	While Grole

Transfer Data Register (DR) to Wiper Counter Register (WCR)

CS Falling	Ι.		e Ty tifie				evice dress				ode			OR/Ba		1	CS Rising
Edge	0	1	0	1	0	0	A1	A0	1	1	0	1	RB	RA	0	0	Edge

Increment/Decrement Wiper Counter Register (WCR)

CS	De	evice	е Ту	ре	e Device			Instruction DR/Bank				Increment/Decrement							CS						
Falling		den	tifie	r		Add	dresse	es		Opc	ode	Э	A	ddre	esse	es	((Sent	by	Mas	ster	on	SDA)	Rising
Edge	0	1	0	1	0	0	A1	A0	0	0	1	0	Χ	Χ	0	0	I/D	I/D					I/D	I/D	Edge

Read Status Register (SR)

	CS			э Ту	•		D	evice	!	In	stru	ıctic	n		R/E	3an	k					ata	,			CS
ı	Falling		den	tifie	r		Add	dress	es	(Эрс	ode)	A	ddre	ess	es	l	(S	ent	by	X9:	271	on	SO)	Rising
ı	Edge	0	1	0	1	0	0	A1	A0	0	1	0	1	0	0	0	1	0	0	0	0	0	0	0	WIP	Edge

Notes: (1) "A1 \sim A0": stands for the device addresses sent by the master.

- (2) WCRx refers to wiper position data in the Wiper Counter Register
- (2) "I": stands for the increment operation, SI held HIGH during active SCK phase (high).
- (3) "D": stands for the decrement operation, SI held LOW during active SCK phase (high).
- (4) "X:": Don't Care.

ABSOLUTE MAXIMUM RATINGS

Temperature under bias	65°C to +135°C
Storage temperature	65°C to +150°C
Voltage on SCK any address input	
with respect to V _{SS}	1V to +7V
$\Delta V = (V_H - V_I) $	5.5V
Lead temperature (soldering, 10 see	conds) 300°C
I _W (10 seconds)	±6mA

COMMENT

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only; the functional operation of the device (at these or any other conditions above those listed in the operational sections of this specification) is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

Temp	Min.	Max.
Commercial	0°C	+70°C
Industrial	–40°C	+85°C

Device	Supply Voltage (V _{CC}) ⁽⁴⁾ Limits
X9271	5V ±10%
X9271-2.7	2.7V to 5.5V

ANALOG CHARACTERISTICS (Over recommended industrial operating conditions unless otherwise stated.)

			Li	mits		
Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
R _{TOTAL}	End to End Resistance		100		kΩ	T version
R _{TOTAL}	End to End Resistance		50		kΩ	U version
	End to End Resistance Tolerance			±20	%	
	Power Rating			50	mW	25°C, each pot
I _W	Wiper Current			±3	mA	
R _W	Wiper Resistance			300	Ω	$I_W = \pm 3 \text{mA} @ V_{CC} = 3 \text{V}$
R _W	Wiper Resistance			150	Ω	$I_W = \pm 3 \text{mA} @ V_{CC} = 5 \text{V}$
V _{TERM}	Voltage on any R _H or R _L Pin	V _{SS}		V _{CC}	V	V _{SS} = 0V
	Noise		-120		dBV/√Hz	Ref: 1V
	Resolution		0.4		%	
	Absolute Linearity ⁽¹⁾			±1	MI ⁽³⁾	$R_{w(n)(actual)} - R_{w(n)(expected)}^{(5)}$
	Relative Linearity ⁽²⁾			±0.2	MI ⁽³⁾	$R_{w(n+1)} - [R_{w(n)+Ml}]^{(5)}$
	Temperature Coefficient of R _{TOTAL}		±300		ppm/°C	
	Ratiometric Temp. Coefficient			20	ppm/°C	
C _H /C _L /C _W	Potentiometer Capacitancies		10/10/25		pF	See Macro model

Notes: (1) Absolute linearity is utilized to determine actual wiper voltage versus expected voltage as determined by wiper position when used as a potentiometer.

- (3) MI = RTOT / 255 or $(R_H R_L) / 255$, single pot
- (4) During power up $V_{CC} > V_H$, V_L , and V_W .
- (5) n = 0, 1, 2, ..., 255; m = 0, 1, 2,, 254.

⁽²⁾ Relative linearity is utilized to determine the actual change in voltage between two successive tap positions when used as a potentiometer. It is a measure of the error in step size.

D.C. OPERATING CHARACTERISTICS (Over the recommended operating conditions unless otherwise specified.)

			Lir	nits					
Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions			
I _{CC1}	V _{CC} supply current (active)			400	μА	f _{SCK} = 2.5 MHz, SO = Open, V _{CC} =6V Other Inputs = V _{SS}			
I _{CC2}	V _{CC} supply current (nonvolatile write)		1	5	mA	f _{SCK} = 2.5MHz, SO = Open, V _{CC} =6V Other Inputs = V _{SS}			
I _{SB}	V _{CC} current (standby)			3	μА	$SCK = SI = V_{SS}$, Addr. = V_{SS} , $\overline{CS} = V_{CC} = 6V$			
I _{LI}	Input leakage current			10	μΑ	$V_{IN} = V_{SS}$ to V_{CC}			
I _{LO}	Output leakage current			10	μΑ	$V_{OUT} = V_{SS}$ to V_{CC}			
V _{IH}	Input HIGH voltage	V _{CC} x 0.7		V _{CC} + 1	V				
V _{IL}	Input LOW voltage	-1		V _{CC} x 0.3	V				
V _{OL}	Output LOW voltage			0.4	V	I _{OL} = 3mA			
V _{OH}	Output HIGH voltage	V _{CC} - 0.8			V	$I_{OH} = -1 \text{mA}, V_{CC} \ge +3 \text{V}$			
V _{OH}	Output HIGH voltage	V _{CC} - 0.4			V	$I_{OH} = -0.4$ mA, $V_{CC} \le +3$ V			

ENDURANCE AND DATA RETENTION

Parameter	Min.	Units			
Minimum endurance	100,000	Data changes per bit per register			
Data retention	100	years			

CAPACITANCE

Symbol	Test	Max.	Units	Test Conditions
C _{IN/OUT} ⁽⁶⁾	Input / Output capacitance (SI)	8	pF	V _{OUT} = 0V
C _{OUT} ⁽⁶⁾	Output capacitance (SO)	8	pF	V _{OUT} = 0V
C _{IN} ⁽⁶⁾	Input capacitance (A0, $\overline{\text{CS}}$, $\overline{\text{WP}}$, $\overline{\text{HOLD}}$, and SCK)	6	pF	V _{IN} = 0V

POWER-UP TIMING

Symbol	Parameter	Min.	Max.	Units
t _r V _{CC} ⁽⁶⁾	V _{CC} Power-up rate	0.2	50	V/ms
t _{PUR} ⁽⁷⁾	Power-up to initiation of read operation		1	ms
t _{PUW} ⁽⁷⁾	Power-up to initiation of write operation		50	ms

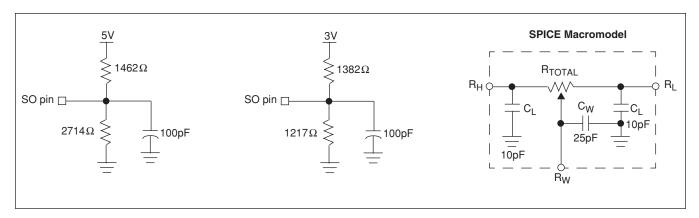
A.C. TEST CONDITIONS

Input Pulse Levels	V _{CC} x 0.1 to V _{CC} x 0.9
Input rise and fall times	10ns
Input and output timing level	V _{CC} x 0.5

Notes: (6) This parameter is not 100% tested

⁽⁷⁾ t_{PUR} and t_{PUW} are the delays required from the time the (last) power supply (V_{CC}-) is stable until the specific instruction can be issued. These parameters are periodically sampled and not 100% tested.

EQUIVALENT A.C. LOAD CIRCUIT



AC TIMING

Symbol	Parameter	Min.	Max.	Units
f _{SCK}	SSI/SPI clock frequency		2.5	MHz
t _{CYC}	SSI/SPI clock cycle time	500		ns
t _{WH}	SSI/SPI clock high time	200		ns
t _{WL}	SSI/SPI clock low time	200		ns
t _{LEAD}	Lead time	250		ns
t _{LAG}	Lag time	250		ns
t _{SU}	SI, SCK, HOLD and CS input setup time	50		ns
t _H	SI, SCK, HOLD and CS input hold time	50		ns
t _{RI}	SI, SCK, HOLD and CS input rise time		2	μs
t _{Fl}	SI, SCK, HOLD and CS input fall time		2	μs
t _{DIS}	SO output disable time	0	250	ns
t _V	SO output valid time		200	ns
t _{HO}	SO output hold time	0		ns
t _{RO}	SO output rise time		100	ns
t _{FO}	SO output fall time		100	ns
t _{HOLD}	HOLD time	400		ns
t _{HSU}	HOLD setup time	100		ns
t _{HH}	HOLD hold time	100		ns
t _{HZ}	HOLD low to output in high Z		100	ns
t _{LZ}	HOLD high to output in low Z		100	ns
T _I	Noise suppression time constant at SI, SCK, HOLD and CS inputs		10	ns
t _{CS}	CS deselect time	2		μs
twpasu	WP, A0 setup time	0		ns
twpah	WP, A0 hold time	0		ns

HIGH-VOLTAGE WRITE CYCLE TIMING

Symbol	Parameter	Тур.	Max.	Units
t _{WR}	High-voltage write cycle time (store instructions)	5	10	ms

XDCP TIMING

Symbol	Parameter	Min.	Max.	Units
t _{WRPO}	Wiper response time after the third (last) power supply is stable	5	10	μs
t _{WRL}	Wiper response time after instruction issued (all load instructions)	5	10	μs

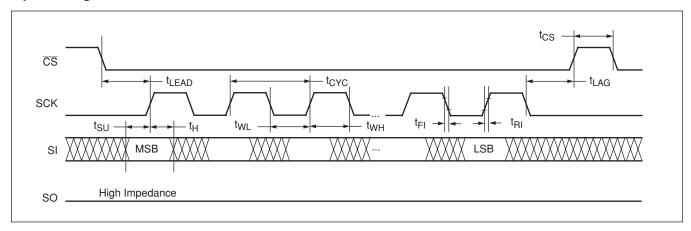
SYMBOL TABLE

REV 1.1.7 2/6/03

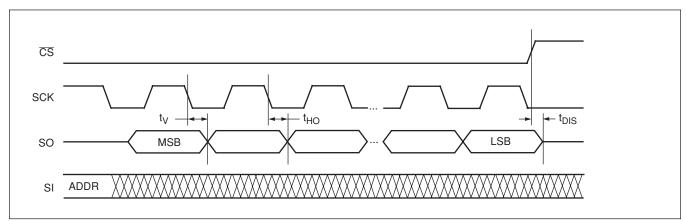
INPUTS	OUTPUTS
Must be steady	Will be steady
May change from Low to High	Will change from Low to High
May change from High to Low	Will change from High to Low
Don't Care: Changes Allowed	Changing: State Not Known
N/A	Center Line is High Impedance
	Must be steady May change from Low to High May change from High to Low Don't Care: Changes Allowed

TIMING DIAGRAMS

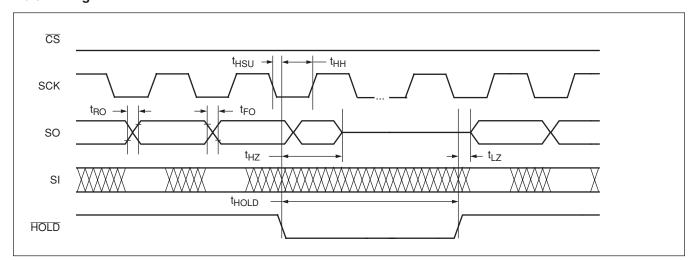
Input Timing



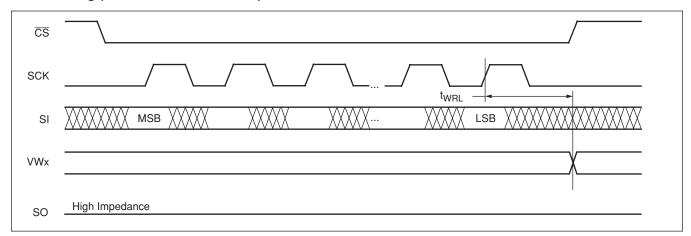
Output Timing



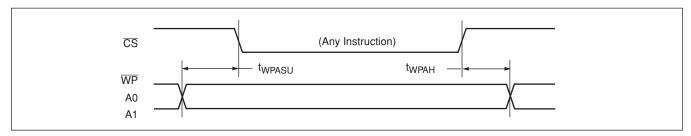
Hold Timing



XDCP Timing (for All Load Instructions)

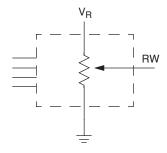


Write Protect and Device Address Pins Timing

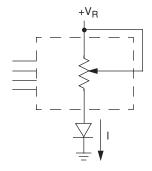


APPLICATIONS INFORMATION

Basic Configurations of Electronic Potentiometers



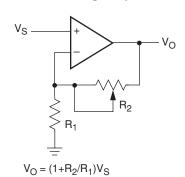
Three terminal Potentiometer; Variable voltage divider



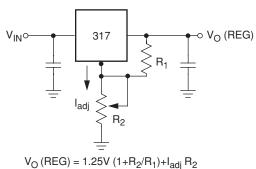
Two terminal Variable Resistor; Variable current

Application Circuits

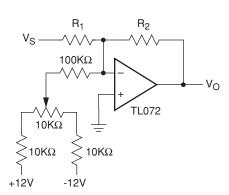
Noninverting Amplifier



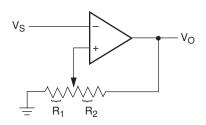
Voltage Regulator



Offset Voltage Adjustment



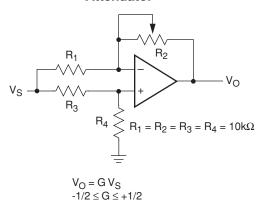
Comparator with Hysterisis

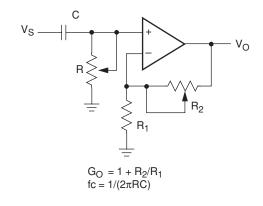


$$\begin{aligned} &V_{UL} = \{R_1/(R_1 + R_2)\} \ V_O(max) \\ &RL_L = \{R_1/(R_1 + R_2)\} \ V_O(min) \end{aligned}$$

Application Circuits (continued)

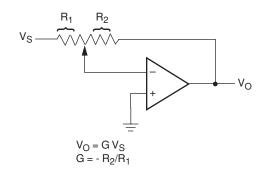
Attenuator



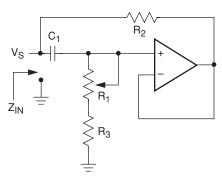


Filter

Inverting Amplifier

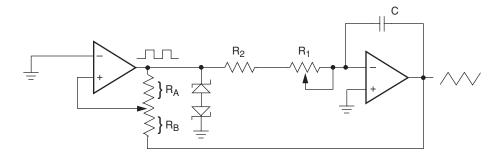


Equivalent L-R Circuit



$$Z_{IN} = R_2 + s R_2 (R_1 + R_3) C_1 = R_2 + s Leq (R_1 + R_3) >> R_2$$

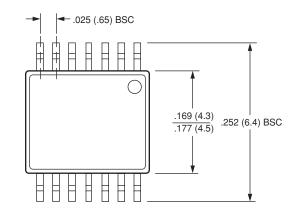
Function Generator

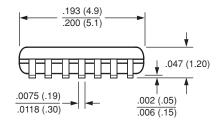


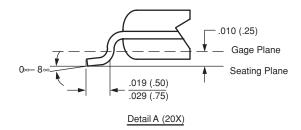
 $\begin{array}{l} \text{frequency} \propto R_1,\,R_2,\,C \\ \text{amplitude} \propto R_A,\,R_B \end{array}$

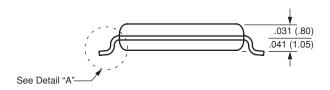
PACKAGING INFORMATION

14-LEAD PLASTIC, TSSOP, PACKAGE TYPE V



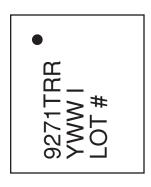




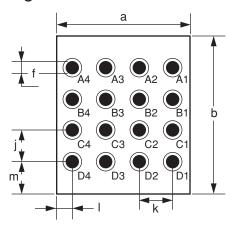


NOTE: ALL DIMENSIONS IN INCHES (IN PARENTHESES IN MILLIMETERS)

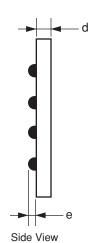
16-Bump Chip Scale Package (CSP B16) Package Outline Drawing

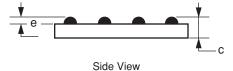


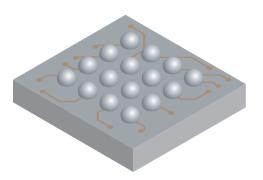




Bottom View (Bumped Side)







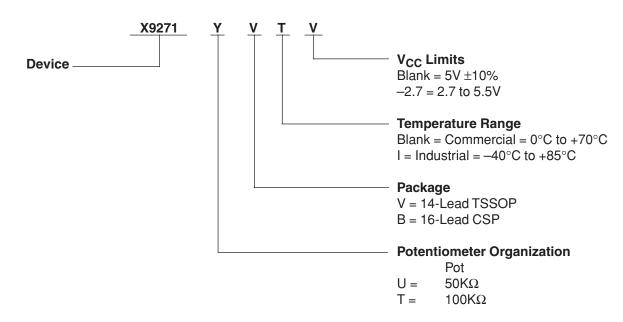
Package Dimensions

		Millimeters		
	Symbol	Min	Nominal	Max
Package Width	а	2.593	2.623	2.653
Package Length	b	2.771	2.801	2.831
Package Height	С	0.644	0.677	0.710
Body Thickness	d	0.444	0.457	0.470
Ball Height	е	0.200	0.220	0.240
Ball Diameter	f	0.300	0.320	0.340
Ball Pitch – Width	j		0.5	
Ball Pitch – Length	k		0.5	
Ball to Edge Spacing – Width	I	0.537	0.562	0.587
Ball to Edge Spacing - Length	m	0.626	0.651	0.676

Ball Matrix:

	4	3	2	1
Α	A0	Vcc	R _L	R _H
В	CS	SO	NC	R _W
С	SCK	NC	NC	HOLD
D	SI	Vss	WP	A1

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